

PATENT
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IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

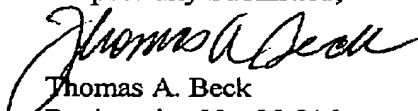
In re Application of : D.Y. Shih, et al.
Serial Number : 09/254,769
Filing Date : March 11, 1999
Examiner : V. Nguyen
Group Art Unit : 2829
For : WAFER SCALE HIGH DENSITY
PROBE ASSEMBLY, APPARATUS FOR USE
THEREOF AND METHODS OF
FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Notice to correct the drawings in the above-identified application,
please insert the enclosed formal drawings comprising Figures 1 - 19 including Figure 6(a).

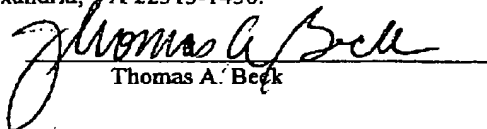
Respectfully Submitted,


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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being transmitted by facsimile on the date shown below to the United States Patent Office Examiner responsible for this case at (571) 273 - 8300 and is addressed to the Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

October 5, 2006


Thomas A. Beck